PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1304-01  Date: April 29, 2013
Product Affected: LDS6120PVGI, LDS6120PVGI8 built in SSOP-48
Date Effective: July 29, 2013

MEANS OF DISTINGUISHING CHANGED DEVICES:
- Product Mark
- Lot # will have “P” prefix
- Back Mark
- Date Code
- Other

Contact: IDT PCN DESK  E-mail: pcndesk@idt.com
Attachment: Yes  No
Samples: Samples are available now.

DESCRIPTION AND PURPOSE OF CHANGE:
Die Technology
Wafer Fabrication Process
Assembly Process
Equipment
Material
Testing
Manufacturing Site
Data Sheet
Other

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device type LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family.

There is no change to the moisture performance.

RELIABILITY/QUALIFICATION SUMMARY:
There is no expected change to the product quality and reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: __________________________  ☐ Approval for shipments prior to effective date.
Name/Date: __________________________  E-Mail Address: __________________________
Title: __________________________  Phone#/Fax#: __________________________

CUSTOMER COMMENTS:
_________________________________________________________________________________
_________________________________________________________________________________
_________________________________________________________________________________

IDT ACKNOWLEDGMENT OF RECEIPT:
RECD. BY: __________________________  DATE: __________________________
ATTACHMENT 1 - PCN # : A1304-01

PCN Type: Alternate Assembly Location

Data Sheet Change: None. No change in moisture sensitivity level (MSL).

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device types LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family.

The material set details of the current Assembly location is shown in the table below. The die attach used at ATP is qualified IDT material. There is no change from the existing qualified lead frame material, lead finish, mold compound and wire for this alternate assembly site.

There is no change to the moisture performance using the assembly material sets as listed in the below table.

<table>
<thead>
<tr>
<th>Description</th>
<th>Existing</th>
<th>Add</th>
</tr>
</thead>
<tbody>
<tr>
<td>Assembly Location</td>
<td>PT Unisem, Indonesia</td>
<td>Amkor, Philippines</td>
</tr>
<tr>
<td>Assembly Materials</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Die Attach: CRM1076NS</td>
<td></td>
<td>Ablestik 8290</td>
</tr>
<tr>
<td>Wire: Au Wire</td>
<td></td>
<td>Au Wire</td>
</tr>
<tr>
<td>Mold Compound: G600</td>
<td></td>
<td>G600</td>
</tr>
<tr>
<td>Lead Frame: Copper Alloy</td>
<td></td>
<td>Copper Alloy</td>
</tr>
<tr>
<td>Plating: Matte 100% Sn</td>
<td></td>
<td>Matte 100% Sn</td>
</tr>
</tbody>
</table>
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Qualification Information and Qualification Data:

Qualification Test Plans and Results :

**Qual Plan & Results:** The qualification was performed in accordance with JEDEC47 recommended tests

**Qual Vehicle:** Device 9P946AFLF SSOP-48 (3 lots)

<table>
<thead>
<tr>
<th>Test Description</th>
<th>Test Method</th>
<th>Lot 1</th>
<th>Lot 2</th>
<th>Lot 3</th>
</tr>
</thead>
<tbody>
<tr>
<td>* HAST - biased (130 °C/85% RH, 100 Hrs)</td>
<td>JESD22-A110</td>
<td>25/0</td>
<td>25/0</td>
<td>25/0</td>
</tr>
<tr>
<td>* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)</td>
<td>JESD22-A104</td>
<td>25/0</td>
<td>25/0</td>
<td>25/0</td>
</tr>
<tr>
<td>* Pressure Cooker (121°C / 2 ATM, 168 hours)</td>
<td>JESD22-A102</td>
<td>25/0</td>
<td>25/0</td>
<td>25/0</td>
</tr>
<tr>
<td>High Temp. Storage Test (150 °C, 1000 Hrs)</td>
<td>JESD22-A103</td>
<td>25/0</td>
<td>25/0</td>
<td>25/0</td>
</tr>
</tbody>
</table>

Note:
* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test